



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Harrison et al.

**Serial No.:** 10/072,743

**Filed:** February 7, 2002

**For:** METHOD OF FABRICATING AN  
INTEGRATED CIRCUIT PACKAGE

**Confirmation No.:** 4046

**Examiner:** D. Nguyen

**Group Art Unit:** 3729

**Attorney Docket No.:** 2269-3758.2US  
(97-0153.01/US)

**Notice of Allowance Mailed:**

April 26, 2004

**Express Mail Mailing Label No.:** EL 994842523 US

**Date of Deposit with USPS:** July 21, 2004

**Person making Deposit:** Christopher Haughton

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Title** appear on page 3 of this paper.

**Amendments to the Specification** begin on page 4 of this paper.

**Amendments to the Abstract** appear on page 7 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 8 of this paper.

**Remarks** begin on page 12 of this paper.

IN THE TITLE:

The title was previously amended by Amendment dated November 5, 2003. Pursuant to 37 C.F.R. §§ 1.121 and 1.25 (as amended to date), please enter the title as previously amended (shown below):

**~~RADIUSED LEADFRAME~~**  
**METHOD OF FABRICATING AN INTEGRATED CIRCUIT PACKAGE**